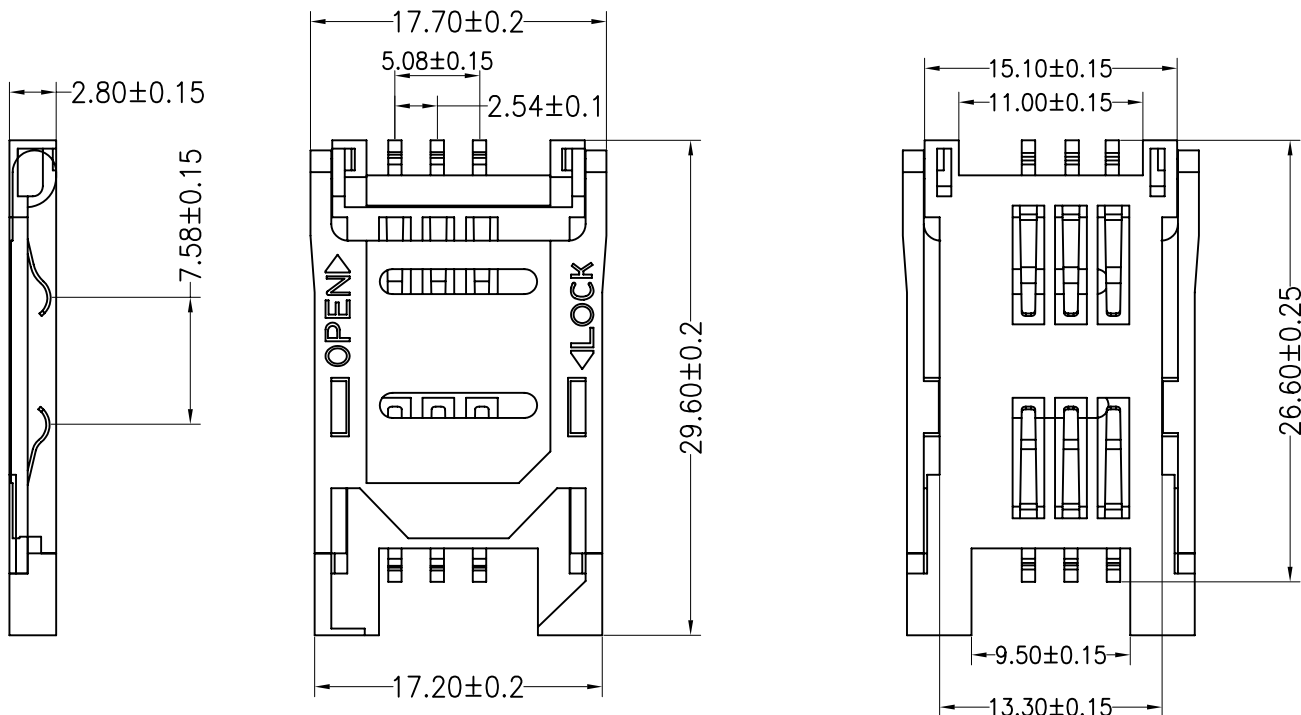


HSF RoHS

SPECIFICATIONS

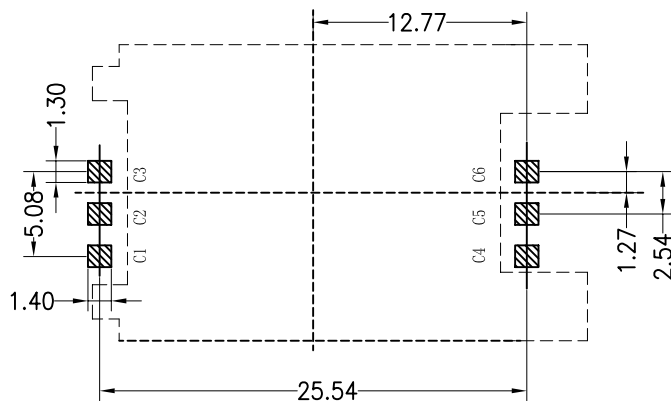
Current Rating: 3 Amps
 Insulator body: LCP
 Insulator Resistance: 1000MΩ Min
 Dielectric Withstanding: DC 500V
 Withstanding Voltage: AC 1000V
 Contact Resistance: 20mΩ Max
 Durability: 100gf Cycls Min
 Contact Material: Copper alloy
 Finish: Tin gold or Duplex plated
 Standard: Gold flash all over Nickel
 Operation Temperature: -40° to +105°
 Max. Processing Temp: 230°C for 30-60 seconds
 (260°C for 10 seconds)



Ordering Information

7420 06 M 2 XX N B X 01

No. of Pins Per Row 06=6P	Connector Type M=SMT	Contact Plating G0: Gold Flash G2: 1.5U" Gold G3: 2U" Gold G4: 3U" Gold G5: 5U" Gold S0: Gold Flash/Tin S2: 3U" Gold/Tin S3: 5U" Gold/Tin	Insulator Color B=Black	Packing T=Tube R=Reel
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PCB LAYOUT

				OPERATION		DRAW	YiYuSheng	13.05.10	SCALE	FIT	JiLN ® 深圳市锦凌电子有限公司 SHENZHEN JINLING ELECTRONIC CO.,LTD Tel: 86-755-2997-5806/5802 Fax: 86-755-2997-5992	
				X.X	±0.30				UNIT	mm		
				X.XX	±0.20	CHECK		SIZE	A4	PART NO.		742006M2XXNBX01
				X.XXX	±0.10	APPROVE		SHEET	1/1	TITLE:		SIM 6P Card Without Post
				Angle	±3°			PROJ.	◆	Customer:		
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	DIM	TOL							